Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.010”**

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**.010”**

**Top Material: Al**

**Backside Material: AuAs**

**Bond Pad Size = .0035 x .0035”**

**Backside Potential: COLLECTOR**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .010” X .010” DATE: 9/7/21**

**MFG: SILICON SUPPLIES THICKNESS .008” P/N: 2N2907A**

**DG 10.1.2**

#### Rev B, 7/1